

In the claims:

Claims 1 to 20 (canceled).

Claim 21 (previously amended) A process of providing a high density module produced by a process comprising the steps of:

providing a circuit board having a substantially planar top surface for connection to at least one integrated circuit package; and

electrically connecting at least one integrated circuit package having a major surface and side minor surfaces extending from said major surface, at least one of said side surfaces having electrical side surface terminals thereon in intimate contact with and electrically connected to said printed circuit board at said top surface.

Claim 22 (previously amended) The process as recited in claim 21 further including the step of electrically and perpendicularly connecting at least two integrated circuit packages to said circuit board.

Claim 23 (previously amended) The process as recited in claim 21 further including the step of disposing a solder ball between said side surface terminal of said integrated circuit package and said top of said circuit board.

Claim 24 (previously amended) The process as recited in claim 21 further including the step of disposing solder columns between said integrated circuit and said top of said circuit board.

Claim 25 (previously amended) The process as recited in claim 21 further including the step of integrally attaching at least three tabs to said circuit board.